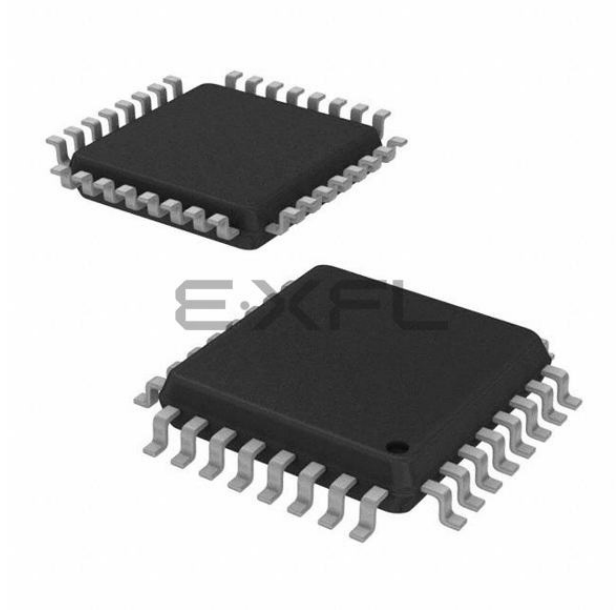

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Program Memory Type	FLASH
EEPROM Size	1.5K x 8
RAM Size	4K x 8
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Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12gn48f1vlcr

Chapter 1
Device Overview MC9S12G-Family

Chapter 19
Pulse-Width Modulator (S12PWM8B8CV2)

Chapter 20
Serial Communication Interface (S12SCIV5)

Table 1-24. 64-Pin LQFP Pinout for S12GA96 and S12GA128

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
28	PT4	IOC4	—	—	—	V_{DDX}	PERT/PPST	Disabled
29	PT3	IOC3	—	—	—	V_{DDX}	PERT/PPST	Disabled
30	PT2	IOC2	—	—	—	V_{DDX}	PERT/PPST	Disabled
31	PT1	IOC1	$\overline{IRQ}$	—	—	V_{DDX}	PERT/PPST	Disabled
32	PT0	IOC0	$\overline{XIRQ}$	—	—	V_{DDX}	PERT/PPST	Disabled
33	PAD0	KWAD0	AN0	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
34	PAD8	KWAD8	AN8	—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
35	PAD1	KWAD1	AN1	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
36	PAD9	KWAD9	AN9	—	—	V_{DDA}	PER0ADPPS0AD	Disabled
37	PAD2	KWAD2	AN2	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
38	PAD10	KWAD10	AN10	—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
39	PAD3	KWAD3	AN3	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
40	PAD11	KWAD11	AN11	—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
41	PAD4	KWAD4	AN4	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
42	PAD12	KWAD12		—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
43	PAD5	KWAD5	AN5	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
44	PAD13	KWAD13		—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
45	PAD6	KWAD6	AN6	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
46	PAD14	KWAD14		—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
47	PAD7	KWAD7	AN7	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
48	PAD15	KWAD15		—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
49	VRH	—	—	—	—	—	—	—
50	VDDA	—	—	—	—	—	—	—
51	VSSA	—	—	—	—	—	—	—
52	PS0	RXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
53	PS1	TXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
54	PS2	RXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
55	PS3	TXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
56	PS4	MISO0	—	—	—	V_{DDX}	PERS/PPSS	Up

1.8.7.3 Pinout 100-Pin LQFP

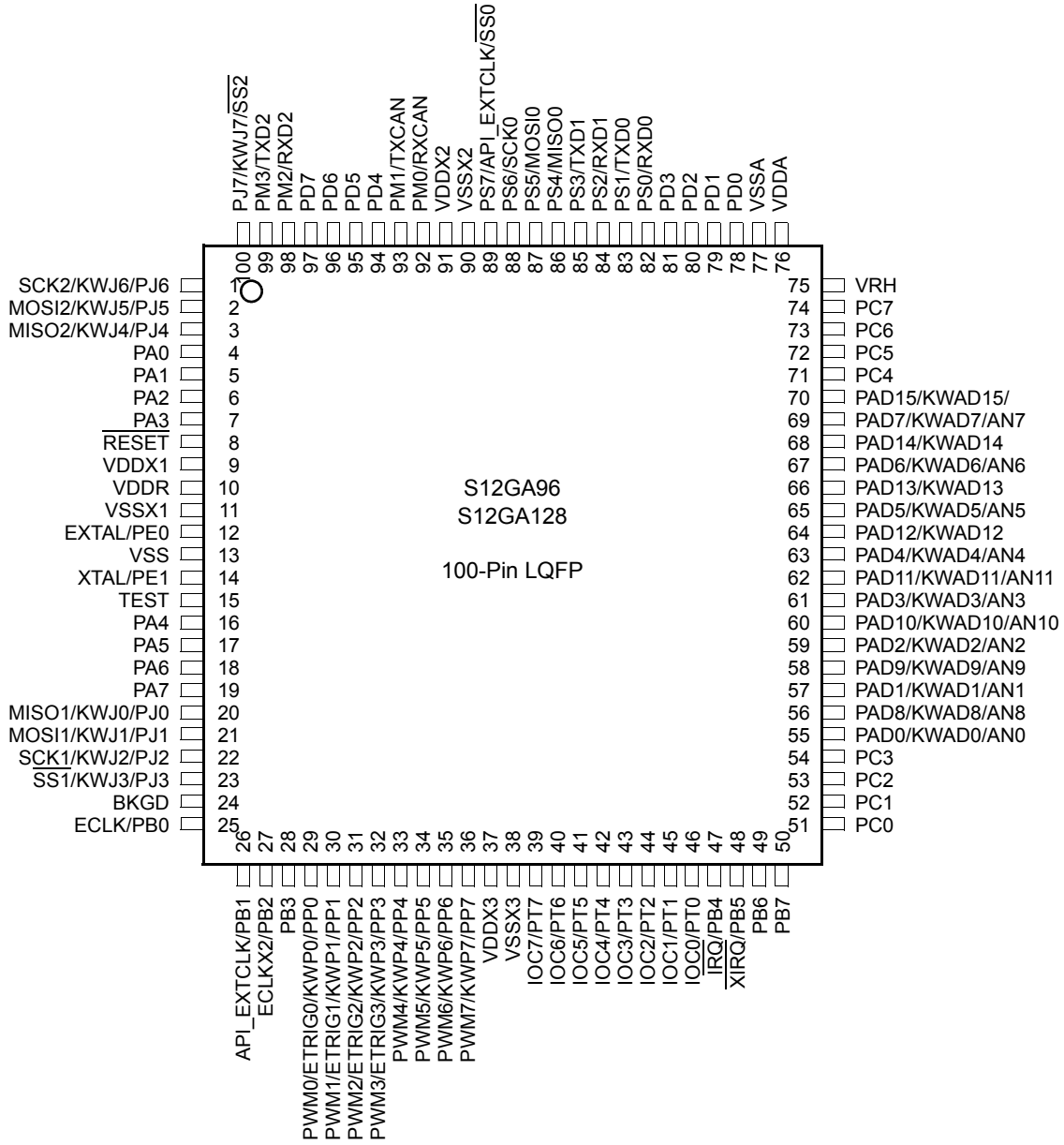


Figure 1-20. 100-Pin LQFP Pinout for S12GA96 and S12GA128

Table 1-29. 48-Pin LQFP Pinout for S12GA192 and S12GA240

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
30	PAD10	KWAD10	AN10	DACU1	AMP1	V_{DDA}	PER0AD/PPS0AD	Disabled
31	PAD3	KWAD3	AN3	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
32	PAD11	KWAD11	AN11	DACU0	AMP0	V_{DDA}	PER0AD/PPS0AD	Disabled
33	PAD4	KWAD4	AN4	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
34	PAD5	KWAD5	AN5	—	—	V_{DDA}	PER1AD/PPS0AD	Disabled
35	PAD6	KWAD6	AN6	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
36	PAD7	KWAD7	AN7	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
37	VDDA	VRH	—	—	—	—	—	—
38	VSSA	—	—	—	—	—	—	—
39	PS0	RXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
40	PS1	TXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
41	PS2	RXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
42	PS3	TXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
43	PS4	MISO0	—	—	—	V_{DDX}	PERS/PPSS	Up
44	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
45	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
46	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
47	PM0	RXD2	RXCAN	—	—	V_{DDX}	PERM/PPSM	Disabled
48	PM1	TXD2	TXCAN	—	—	V_{DDX}	PERM/PPSM	Disabled

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

Table 2-4. Signals and Priorities

Legend	
?	Signal available on pin
?	Routing option on pin
?	Routing reset location
	Not available on pin

Port	Pin	Signal	Signals per Device and Package (signal priority on pin from top to bottom)																				I/O	Description
			GA240 / GA192	G240 / G192	G128 / GA128 / G96 / GA96	GA240 / GA192	G240 / G192	G128 / GA128 / G96 / GA96	G64 / GA64 / G48 / GA48	GN48	GA240 / GA192	G240 / G192	G128 / GA128 / G96 / GA96	G64 / GA64 / G48 / GA48	GN48	GN32 / GNA32	GN16 / GNA16	G64 / G48	GN48	GN32	GN16	GN32	GN16		
			100			64					48							32				20			
E	PE1	XTAL	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	-	CPMU OSC signal
		TXD0																				?	?	I/O	SCI transmit
		IOC3																				?	?	I/O	Timer channel
		PWM1																				?	?	O	PWM channel
		ETRIG1																				?	?	I	ADC external trigger
		[PE1]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	GPIO
	PE0	EXTAL	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	-	CPMU OSC signal
		RXD0																				?	?	I	SCI receive
		IOC2																				?	?	I/O	Timer channel
		PWM0																				?	?	O	PWM channel
		ETRIG0																				?	?	I	ADC external trigger
		[PE0]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	GPIO
T	PT7-PT6	IOC7-IOC6	?	?	?	?	?	?																I/O	Timer channel
		[PTT7:PTT6]	?	?	?	?	?	?	?	?														I/O	GPIO
	PT5-PT4	IOC5-IOC4	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?							I/O	Timer channel
		[PTT5:PTT4]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?							I/O	GPIO
	PT3-PT2	IOC3-IOC2	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?			I/O	Timer channel
		[PTT3:PTT2]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?			I/O	GPIO
	PT1	$\overline{\text{IRQ}}$				?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I	Maskable level- or falling-edge sensitive interrupt
		IOC1	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	Timer channel
		[PTT1]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	GPIO
	PT0	$\overline{\text{XIRQ}}$				?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I	Non-maskable level-sensitive interrupt
		IOC0	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	Timer channel
		[PTT0]	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	?	I/O	GPIO

2.4.3.18 Port T Pull Device Enable Register (PERT)

Address 0x0244 (G1, G2) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R W	PERT7	PERT6	PERT5	PERT4	PERT3	PERT2	PERT1	PERT0
Reset	0	0	0	0	0	0	0	0

Address 0x0244 (G3) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0	0	PERT5	PERT4	PERT3	PERT2	PERT1	PERT0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-19. Port T Pull Device Enable Register (PERT)

[1] Read: Anytime
Write: Anytime

Table 2-38. PERT Register Field Descriptions

Field	Description
7-2 PERT	**Port T pull device enable**—Enable pull device on input pin This bit controls whether a pull device on the associated port input pin is active. If a pin is used as output this bit has no effect. The polarity is selected by the related polarity select register bit. 1 Pull device enabled 0 Pull device disabled
1 PERT	**Port T pull device enable**—Enable pull device on input pin This bit controls whether a pull device on the associated port input pin is active. The polarity is selected by the related polarity select register bit. If this pin is used as IRQ only a pullup device can be enabled. 1 Pull device enabled 0 Pull device disabled
0 PERT	**Port T pull device enable**—Enable pull device on input pin This bit controls whether a pull device on the associated port input pin is active. The polarity is selected by the related polarity select register bit. If this pin is used as XIRQ only a pullup device can be enabled. 1 Pull device enabled 0 Pull device disabled

Read: DBGACTL if COMRV[1:0] = 00
DBGBCTL if COMRV[1:0] = 01
DBGCCTL if COMRV[1:0] = 10

Write: DBGACTL if COMRV[1:0] = 00 and DBG not armed
DBGBCTL if COMRV[1:0] = 01 and DBG not armed
DBGCCTL if COMRV[1:0] = 10 and DBG not armed

Table 8-22. DBGXCTL Field Descriptions

Field	Description
7 SZE (Comparators A and B)	**Size Comparator Enable Bit** — The SZE bit controls whether access size comparison is enabled for the associated comparator. This bit is ignored if the TAG bit in the same register is set. 0 Word/Byte access size is not used in comparison 1 Word/Byte access size is used in comparison
6 SZ (Comparators A and B)	**Size Comparator Value Bit** — The SZ bit selects either word or byte access size in comparison for the associated comparator. This bit is ignored if the SZE bit is cleared or if the TAG bit in the same register is set. 0 Word access size is compared 1 Byte access size is compared
5 TAG	**Tag Select**— This bit controls whether the comparator match has immediate effect, causing an immediate state sequencer transition or tag the opcode at the matched address. Tagged opcodes trigger only if they reach the execution stage of the instruction queue. 0 Allow state sequencer transition immediately on match 1 On match, tag the opcode. If the opcode is about to be executed allow a state sequencer transition
4 BRK	**Break**— This bit controls whether a comparator match terminates a debug session immediately, independent of state sequencer state. To generate an immediate breakpoint the module breakpoints must be enabled using the DBGC1 bit DBGBRK. 0 The debug session termination is dependent upon the state sequencer and trigger conditions. 1 A match on this channel terminates the debug session immediately; breakpoints if active are generated, tracing, if active, is terminated and the module disarmed.
3 RW	**Read/Write Comparator Value Bit** — The RW bit controls whether read or write is used in compare for the associated comparator. The RW bit is not used if RWE = 0. This bit is ignored if the TAG bit in the same register is set. 0 Write cycle is matched1Read cycle is matched
2 RWE	**Read/Write Enable Bit** — The RWE bit controls whether read or write comparison is enabled for the associated comparator.This bit is ignored if the TAG bit in the same register is set 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
1 NDB (Comparator A)	**Not Data Bus** — The NDB bit controls whether the match occurs when the data bus matches the comparator register value or when the data bus differs from the register value. This bit is ignored if the TAG bit in the same register is set. This bit is only available for comparator A. 0 Match on data bus equivalence to comparator register contents 1 Match on data bus difference to comparator register contents
0 COMPE	Determines if comparator is enabled 0 The comparator is not enabled 1 The comparator is enabled

Table 8-23 shows the effect for RWE and RW on the comparison conditions. These bits are ignored if the corresponding TAG bit is set since the match occurs based on the tagged opcode reaching the execution stage of the instruction queue.

is generated. Configuring CompA and CompC the same, it is possible to generate a breakpoint on the third consecutive occurrence of event M0 without a reset M1.

Figure 8-40. Scenario 10a

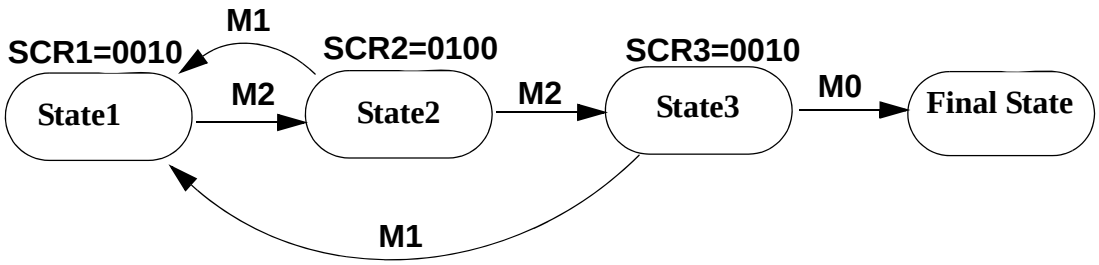
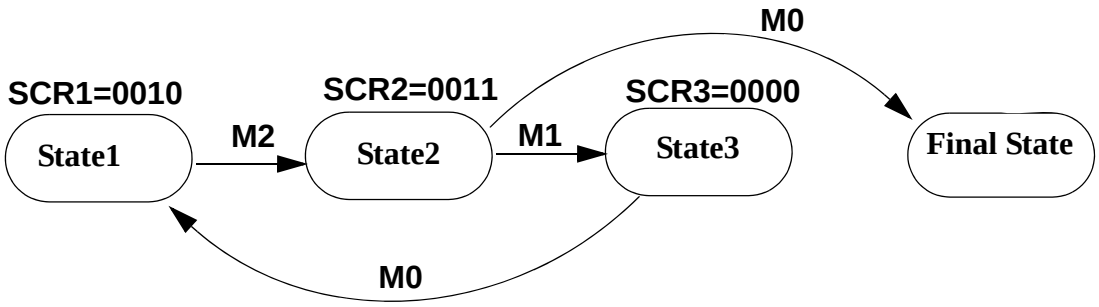


Figure 8-41. Scenario 10b



Scenario 10b shows the case that after M2 then M1 must occur before M0. Starting from a particular point in code, event M2 must always be followed by M1 before M0. If after any M2, event M0 occurs before M1 then a trigger is generated.

13.3.2.6 ATD Control Register 5 (ATDCTL5)

Writes to this register will abort current conversion sequence and start a new conversion sequence. If the external trigger function is enabled (ETRIGE=1) an initial write to ATDCTL5 is required to allow starting of a conversion sequence which will then occur on each trigger event. Start of conversion means the beginning of the sampling phase.

Module Base + 0x0005

	7	6	5	4	3	2	1	0
R	0	SC	SCAN	MULT	CD	CC	CB	CA
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 13-8. ATD Control Register 5 (ATDCTL5)

Read: Anytime

Write: Anytime

Table 13-14. ATDCTL5 Field Descriptions

Field	Description
6 SC	**Special Channel Conversion Bit** — If this bit is set, then special channel conversion can be selected using CD, CC, CB and CA of ATDCTL5. Table 13-15 lists the coding. 0 Special channel conversions disabled 1 Special channel conversions enabled
5 SCAN	**Continuous Conversion Sequence Mode** — This bit selects whether conversion sequences are performed continuously or only once. If the external trigger function is enabled (ETRIGE=1) setting this bit has no effect, thus the external trigger always starts a single conversion sequence. 0 Single conversion sequence 1 Continuous conversion sequences (scan mode)
4 MULT	**Multi-Channel Sample Mode** — When MULT is 0, the ATD sequence controller samples only from the specified analog input channel for an entire conversion sequence. The analog channel is selected by channel selection code (control bits CD/CC/CB/CA located in ATDCTL5). When MULT is 1, the ATD sequence controller samples across channels. The number of channels sampled is determined by the sequence length value (S8C, S4C, S2C, S1C). The first analog channel examined is determined by channel selection code (CD, CC, CB, CA control bits); subsequent channels sampled in the sequence are determined by incrementing the channel selection code or wrapping around to AN0 (channel 0). 0 Sample only one channel 1 Sample across several channels
3–0 CD, CC, CB, CA	**Analog Input Channel Select Code** — These bits select the analog input channel(s). Table 13-15 lists the coding used to select the various analog input channels. In the case of single channel conversions (MULT=0), this selection code specifies the channel to be examined. In the case of multiple channel conversions (MULT=1), this selection code specifies the first channel to be examined in the conversion sequence. Subsequent channels are determined by incrementing the channel selection code or wrapping around to AN0 (after converting the channel defined by the Wrap Around Channel Select Bits WRAP3-0 in ATDCTL0). When starting with a channel number higher than the one defined by WRAP3-0 the first wrap around will be AN11 to AN0.

edge or level sensitive with polarity control. Table 16-23 gives a brief description of the different combinations of control bits and their effect on the external trigger function.

In order to avoid maybe false trigger events please enable the external digital input via ATDDIEN register first and in the following enable the external trigger mode by bit ETRIGE.

Table 16-23. External Trigger Control Bits

ETRIGLE	ETRIGP	ETRIGE	SCAN	Description
X	X	0	0	Ignores external trigger. Performs one conversion sequence and stops.
X	X	0	1	Ignores external trigger. Performs continuous conversion sequences.
0	0	1	X	Trigger falling edge sensitive. Performs one conversion sequence per trigger.
0	1	1	X	Trigger rising edge sensitive. Performs one conversion sequence per trigger.
1	0	1	X	Trigger low level sensitive. Performs continuous conversions while trigger level is active.
1	1	1	X	Trigger high level sensitive. Performs continuous conversions while trigger level is active.

In either level or edge sensitive mode, the first conversion begins when the trigger is received.

Once ETRIGE is enabled a conversion must be triggered externally after writing to ATDCTL5 register.

During a conversion in edge sensitive mode, if additional trigger events are detected the overrun error flag ETORF is set.

If level sensitive mode is active and the external trigger de-asserts and later asserts again during a conversion sequence, this does not constitute an overrun. Therefore, the flag is not set. If the trigger is left active in level sensitive mode when a sequence is about to complete, another sequence will be triggered immediately.

16.4.2.2 General-Purpose Digital Port Operation

Each ATD input pin can be switched between analog or digital input functionality. An analog multiplexer makes each ATD input pin selected as analog input available to the A/D converter.

The pad of the ATD input pin is always connected to the analog input channel of the analog mulitplexer.

Each pad input signal is buffered to the digital port register.

This buffer can be turned on or off with the ATDDIEN register for each ATD input pin.
This is important so that the buffer does not draw excess current when an ATD input pin is selected as analog input to the ADC12B16C.

17.3.4 AMPM Input Pin

This analog pin is used as input for the operational amplifier negative input pin, if the according mode is selected, see register bit DACM[2:0].

17.4 Memory Map and Register Definition

This sections provides the detailed information of all registers for the DAC_8B5V module.

17.4.1 Register Summary

Figure 17-2 shows the summary of all implemented registers inside the DAC_8B5V module.

NOTE

Register Address = Module Base Address + Address Offset, where the Module Base Address is defined at the MCU level and the Address Offset is defined at the module level.

Address Offset / Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000 DACCTL	R	FVR	DRIVE	0	0	0	DACM[2:0]		
	W								
0x0001 Reserved	R	0	0	0	0	0	0	0	0
	W								
0x0002 DACVOL	R	VOLTAGE[7:0]							
	W								
0x0003 - 0x0006 Reserved	R	0	0	0	0	0	0	0	0
	W								
0x0007 Reserved	R	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
	W								
0x0007 DACDEBUG	R	0	BUF_EN	DAC_EN	S3	S2n	S2p	S1n	S1p
	W								

= Unimplemented

Figure 17-2. DAC_8B5V Register Summaryfv_dac_8b5v_RESERVED

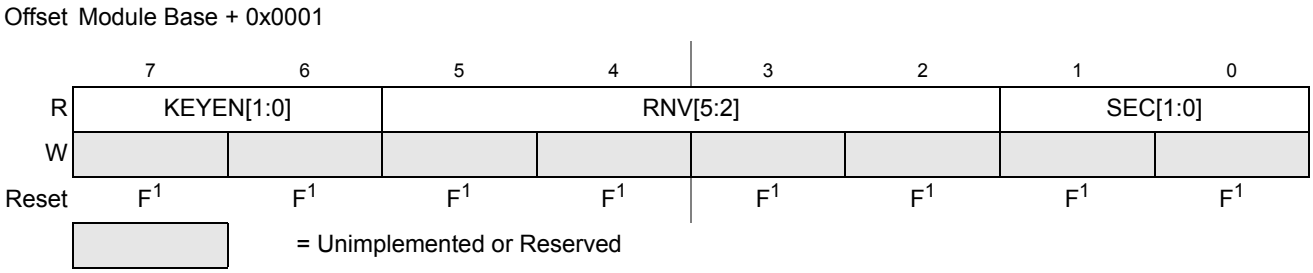


Figure 24-6. Flash Security Register (FSEC)

1 Loaded from IFR Flash configuration field, during reset sequence.

All bits in the FSEC register are readable but not writable.

During the reset sequence, the FSEC register is loaded with the contents of the Flash security byte in the Flash configuration field at global address 0x3_FF0F located in P-Flash memory (see Table 24-4) as indicated by reset condition F in Figure 24-6. If a double bit fault is detected while reading the P-Flash phrase containing the Flash security byte during the reset sequence, all bits in the FSEC register will be set to leave the Flash module in a secured state with backdoor key access disabled.

Table 24-9. FSEC Field Descriptions

Field	Description
7–6 KEYEN[1:0]	**Backdoor Key Security Enable Bits** — The KEYEN[1:0] bits define the enabling of backdoor key access to the Flash module as shown in Table 24-10.
5–2 RNV[5:2]	**Reserved Nonvolatile Bits** — The RNV bits should remain in the erased state for future enhancements.
1–0 SEC[1:0]	**Flash Security Bits** — The SEC[1:0] bits define the security state of the MCU as shown in Table 24-11. If the Flash module is unsecured using backdoor key access, the SEC bits are forced to 10.

Table 24-10. Flash KEYEN States

KEYEN[1:0]	Status of Backdoor Key Access
00	DISABLED
01	DISABLED[1]
10	ENABLED
11	DISABLED

1 Preferred KEYEN state to disable backdoor key access.

Table 24-11. Flash Security States

SEC[1:0]	Status of Security
00	SECURED
01	SECURED[1]
10	UNSECURED
11	SECURED

1 Preferred SEC state to set MCU to secured state.

Chapter 26
48 KByte Flash Module (S12FTMRG48K1V1)

Table 26-1. Revision History

Revision Number	Revision Date	Sections Affected	Description of Changes
V01.04	17 Jun 2010	26.4.6.1/26-899 26.4.6.2/26-900 26.4.6.3/26-900 26.4.6.14/26-910	Clarify Erase Verify Commands Descriptions related to the bits MGSTAT[1:0] of the register FSTAT.
V01.05	20 aug 2010	26.4.6.2/26-900 26.4.6.12/26-907 26.4.6.13/26-909	Updated description of the commands RD1BLK, MLOADU and MLOADF
Rev.1.27	31 Jan 2011	26.3.2.9/26-882	Updated description of protection on Section 26.3.2.9

26.1 Introduction

The FTMRG48K1 module implements the following:

- 48Kbytes of P-Flash (Program Flash) memory
- 1,536bytes of EEPROM memory

The Flash memory is ideal for single-supply applications allowing for field reprogramming without requiring external high voltage sources for program or erase operations. The Flash module includes a memory controller that executes commands to modify Flash memory contents. The user interface to the memory controller consists of the indexed Flash Common Command Object (FCCOB) register which is written to with the command, global address, data, and any required command parameters. The memory controller must complete the execution of a command before the FCCOB register can be written to with a new command.

CAUTION

A Flash word or phrase must be in the erased state before being programmed. Cumulative programming of bits within a Flash word or phrase is not allowed.

The Flash memory may be read as bytes and aligned words. Read access time is one bus cycle for bytes and aligned words. For misaligned words access, the CPU has to perform twice the byte read access command. For Flash memory, an erased bit reads 1 and a programmed bit reads 0.

Figure 26-2. P-Flash Memory Map

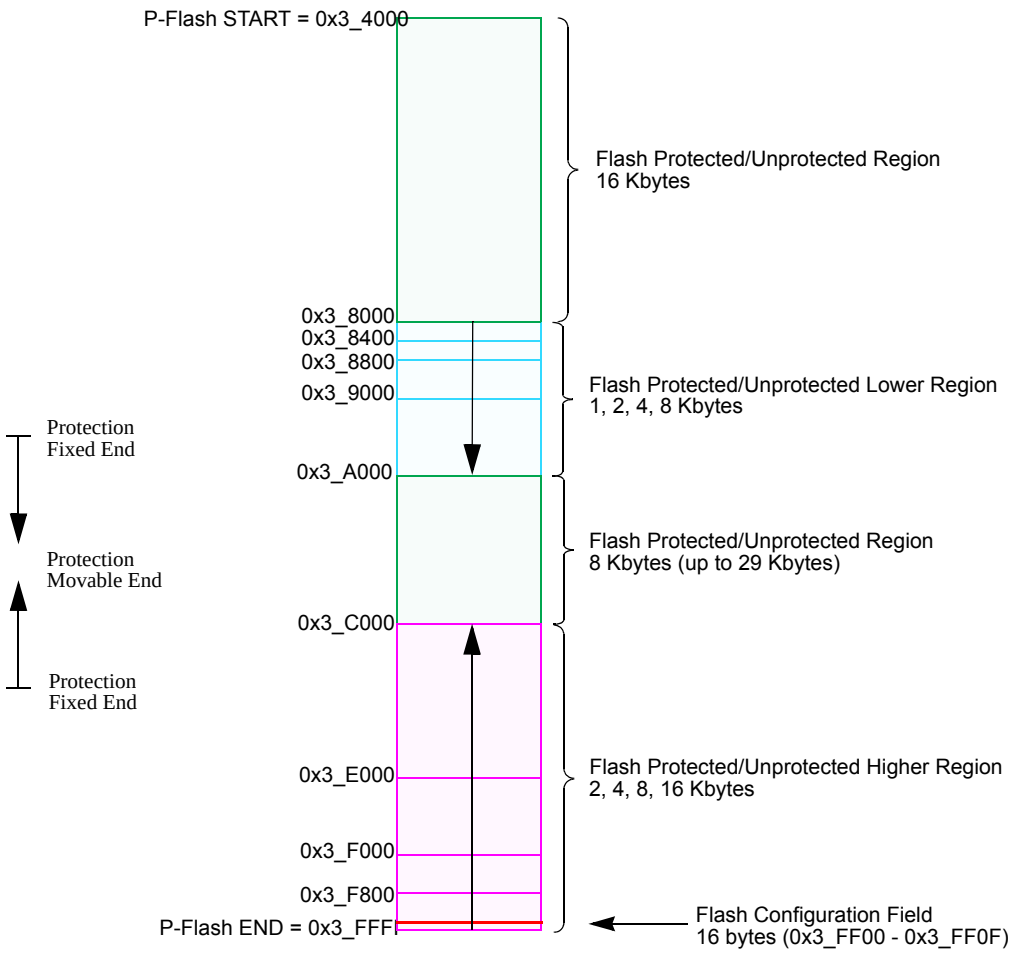


Table 26-5. Program IFR Fields

Global Address	Size (Bytes)	Field Description
0x0_4000 – 0x0_4007	8	Reserved
0x0_4008 – 0x0_40B5	174	Reserved
0x0_40B6 – 0x0_40B7	2	Version ID[1]
0x0_40B8 – 0x0_40BF	8	Reserved
0x0_40C0 – 0x0_40FF	64	Program Once Field Refer to Section 26.4.6.6, “Program Once Command”

[1] Used to track firmware patch versions, see Section 26.4.2

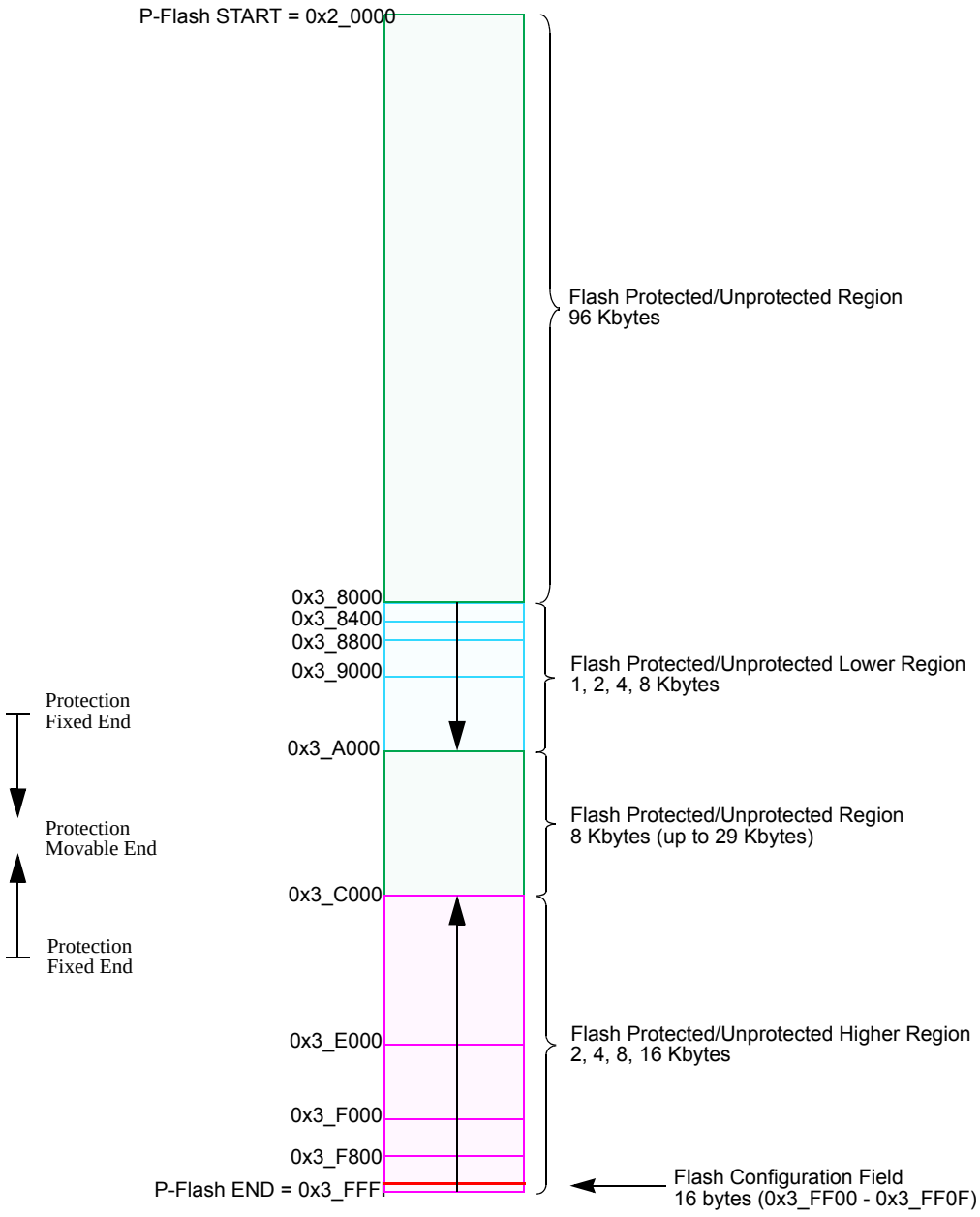


Figure 29-2. P-Flash Memory Map

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0x0_40B6 – 0x0_40B7	2	Version ID[1]

29.4.4.3 Valid Flash Module Commands

Table 29-27 present the valid Flash commands, as enabled by the combination of the functional MCU mode (Normal SingleChip NS, Special Singlechip SS) with the MCU security state (Unsecured, Secured).

Special Singlechip mode is selected by input mmc_ss_mode_ts2 asserted. MCU Secured state is selected by input mmc_secure input asserted.

Table 29-27. Flash Commands by Mode and Security State

FCMD	Command	Unsecured		Secured	
		NS[1]	SS[2]	NS[3]	SS[4]
0x01	Erase Verify All Blocks	*	*	*	*
0x02	Erase Verify Block	*	*	*	*
0x03	Erase Verify P-Flash Section	*	*	*	
0x04	Read Once	*	*	*	
0x06	Program P-Flash	*	*	*	
0x07	Program Once	*	*	*	
0x08	Erase All Blocks		*		*
0x09	Erase Flash Block	*	*	*	
0x0A	Erase P-Flash Sector	*	*	*	
0x0B	Unsecure Flash		*		*
0x0C	Verify Backdoor Access Key	*		*	
0x0D	Set User Margin Level	*	*	*	
0x0E	Set Field Margin Level		*		
0x10	Erase Verify EEPROM Section	*	*	*	
0x11	Program EEPROM	*	*	*	
0x12	Erase EEPROM Sector	*	*	*	

1 Unsecured Normal Single Chip mode
2 Unsecured Special Single Chip mode.
3 Secured Normal Single Chip mode.
4 Secured Special Single Chip mode.

29.4.4.4 P-Flash Commands

Table 29-28 summarizes the valid P-Flash commands along with the effects of the commands on the P-Flash block and other resources within the Flash module.

Table 29-28. P-Flash Commands

FCMD	Command	Function on P-Flash Memory
0x01	Erase Verify All Blocks	Verify that all P-Flash (and EEPROM) blocks are erased.

- VERNUM: Version number. The first version is number 0b_0001 with both 0b_0000 and 0b_1111 meaning ‘none’.

30.4.3 Internal NVM resource (NVMRES)

IFR is an internal NVM resource readable by CPU , when NVMRES is active. The IFR fields are shown in Table 30-5.

The NVMRES global address map is shown in Table 30-6.

30.4.4 Flash Command Operations

Flash command operations are used to modify Flash memory contents.

The next sections describe:

- How to write the FCLKDIV register that is used to generate a time base (FCLK) derived from BUSCLK for Flash program and erase command operations
- The command write sequence used to set Flash command parameters and launch execution
- Valid Flash commands available for execution, according to MCU functional mode and MCU security state.

30.4.4.1 Writing the FCLKDIV Register

Prior to issuing any Flash program or erase command after a reset, the user is required to write the FCLKDIV register to divide BUSCLK down to a target FCLK of 1 MHz. Table 30-8 shows recommended values for the FDIV field based on BUSCLK frequency.

NOTE

Programming or erasing the Flash memory cannot be performed if the bus clock runs at less than 0.8 MHz. Setting FDIV too high can destroy the Flash memory due to overstress. Setting FDIV too low can result in incomplete programming or erasure of the Flash memory cells.

When the FCLKDIV register is written, the FDIVLD bit is set automatically. If the FDIVLD bit is 0, the FCLKDIV register has not been written since the last reset. If the FCLKDIV register has not been written, any Flash program or erase command loaded during a command write sequence will not execute and the ACCERR bit in the FSTAT register will set.

30.4.4.2 Command Write Sequence

The Memory Controller will launch all valid Flash commands entered using a command write sequence.

Before launching a command, the ACCERR and FPVIOL bits in the FSTAT register must be clear (see Section 30.3.2.7) and the CCIF flag should be tested to determine the status of the current command write sequence. If CCIF is 0, the previous command write sequence is still active, a new command write sequence cannot be started, and all writes to the FCCOB register are ignored.

2 These values include the quantization error which is inherently 1/2 count for any A/D converter.

Table A-26. ADC Conversion Performance 3.3V range (Junction Temperature From +150°C To +160°C)

S12GNA16, S12GNA32								
Supply voltage 3.13V < V_{DDA} < 4.5 V, 150°C < T_J < 160°C, V_{REF} = V_{RH} - V_{RL} = V_{DDA}, f_{ADCCLK} = 8.0MHz The values are tested to be valid with no port AD output drivers switching simultaneous with conversions.								
Num	**C**	**Rating[1]**		**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	M	Resolution	12-Bit	LSB		0.80		mV
2	M	Differential Nonlinearity	12-Bit	DNL		±3		counts
3	M	Integral Nonlinearity	12-Bit	INL		±3		counts
4	M	Absolute Error[2]	12-Bit	AE		±4		counts
5	C	Resolution	10-Bit	LSB		3.22		mV
6	C	Differential Nonlinearity	10-Bit	DNL		±1		counts
7	C	Integral Nonlinearity	10-Bit	INL		±1		counts
8	C	Absolute Error[2]	10-Bit	AE		±2		counts
9	C	Resolution	8-Bit	LSB		12.89		mV
10	C	Differential Nonlinearity	8-Bit	DNL		±0.3		counts
11	C	Integral Nonlinearity	8-Bit	INL		±0.5		counts
12	C	Absolute Error[2]	8-Bit	AE		±1		counts

1 The 8-bit and 10-bit mode operation is structurally tested in production test. Absolute values are tested in 12-bit mode.

2 These values include the quantization error which is inherently 1/2 count for any A/D converter.

Table A-27. ADC Conversion Performance 3.3V range (Junction Temperature From –40°C To +150°C)

S12GN16, S12GN32, S12GN48, S12G48, S12G64, S12G96, S12G128, S12G192, and S12G240								
Supply voltage 3.13V < V_{DDA} < 4.5 V, -40°C < T_J < 150°C, V_{REF} = V_{RH} - V_{RL} = V_{DDA}, f_{ADCCLK} = 8.0MHz The values are tested to be valid with no port AD output drivers switching simultaneous with conversions.								
Num	**C**	**Rating[1]**		**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Resolution	10-Bit	LSB		3.22		mV
2	P	Differential Nonlinearity	10-Bit	DNL	-1.5	±1	1.5	counts
3	P	Integral Nonlinearity	10-Bit	INL	-2	±1	2	counts
4	P	Absolute Error[2]	10-Bit[3] 10-Bit[4]	AE	-3 -4	±2 ±2	3 4	counts
5	C	Resolution	8-Bit	LSB		12.89		mV
6	C	Differential Nonlinearity	8-Bit	DNL	-0.5	±0.3	0.5	counts
7	C	Integral Nonlinearity	8-Bit	INL	-1	±0.5	1	counts
8	C	Absolute Error[2]	8-Bit	AE	-1.5	±1	1.5	counts

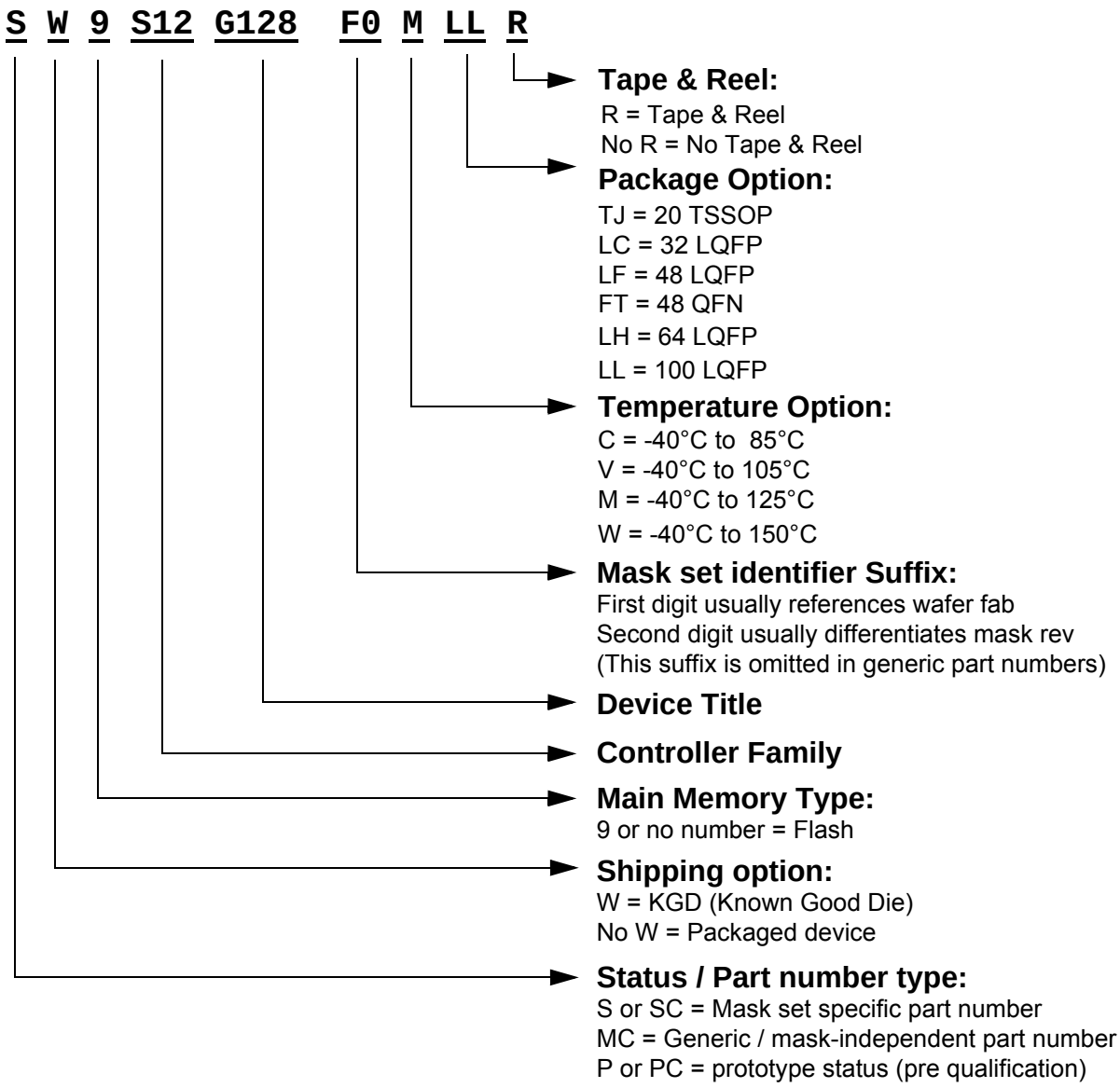

Figure C-1. Order Part Number Example